

L Number	Hits	Search Text	DB	Time stamp
1	116325	15/\$.ccls. or 451/\$.ccls.	USPAT; US-PGPUB	2004/09/22 12:39
2	14671	(15/\$.ccls. or 451/\$.ccls.) and (substrate or wafer or semi-conductor or semiconductor or "semi conductor" or disc)	USPAT; US-PGPUB	2004/09/22 13:01
3	11199	((15/\$.ccls. or 451/\$.ccls.) and (substrate or wafer or semi-conductor or semiconductor or "semi conductor" or disc)) and (pad or brush or bristles or member)	USPAT; US-PGPUB	2004/09/22 13:01
4	122	((15/\$.ccls. or 451/\$.ccls.) and (substrate or wafer or semi-conductor or semiconductor or "semi conductor" or disc)) and ((pad or brush or bristles or member) near (sensor or detect or signal))	USPAT; US-PGPUB	2004/09/22 13:09
5	2427808	substrate or wafer or semi-conductor or semiconductor or "semi conductor" or disc	EPO; JPO; DERWENT	2004/09/22 13:01
6	194437	(substrate or wafer or semi-conductor or semiconductor or "semi conductor" or disc) and (pad or brush or bristles or member)	EPO; JPO; DERWENT	2004/09/22 13:09
7	967	(substrate or wafer or semi-conductor or semiconductor or "semi conductor" or disc) and ((pad or brush or bristles or member) near (sensor or detect or signal))	EPO; JPO; DERWENT	2004/09/22 14:00
8	26	((substrate or wafer or semi-conductor or semiconductor or "semi conductor" or disc) and ((pad or brush or bristles or member) near (sensor or detect or signal))) and (clean or polish)	EPO; JPO; DERWENT	2004/09/22 14:01